

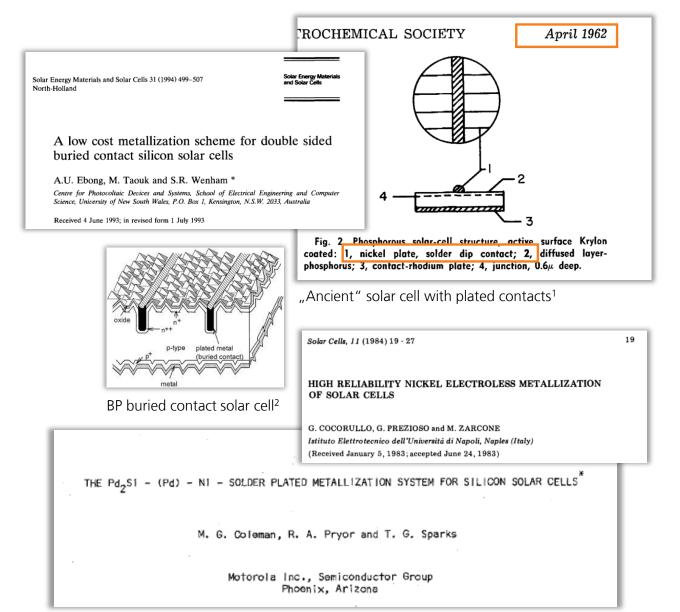
Short history of plating in PV

Plating has been used in PV for a long time

- Very early cells, even at Bell Labs
- Motorola / JPL, NASA
- BP Solar

Motivations for plating

- Technological Advantage
- Cost reduction potential (even in the 80s)
- Coming from evaporated contacts
- Process cost lower, similar advantages
- Silver cost, no mature screen printing...









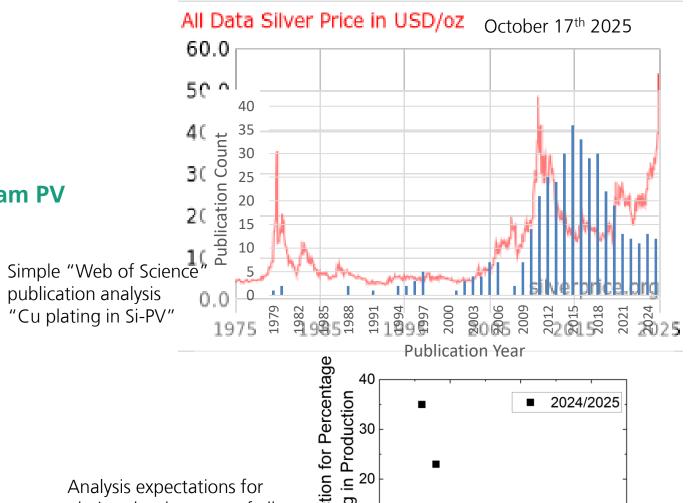
Short history of plating in PV

Few attempts to commercialize in mainstream PV

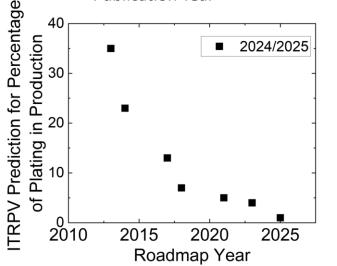
- E.g, "Pluto" cell (Wuxi Suntech)
- R&D in Plating for PV is still strong
- Conincides with Silver price (?)

ITRPV expectations for plating

- Used to be strong
- Currently rather "honorable mention"



plating development of all ITRPV roadmaps so far



Quo vadis plating in PV?

Plating is an endangered species in PV!

- Which category to put plating into?
- Where are it's "ecological" niches?



THE RED LIST CATEGORIES



Extinct (EX): no reasonable doubt that the last individual has died

Extinct in the Wild (EW): known only to survive in captivity, cultivation or well outside its natural range

Critically Endangered (CR): facing extremely high risk of extinction in the wild

Endangered (EN): facing a very high risk of extinction in the wild,

Vulnerable (VU): facing a high risk of extinction in the wild.

Near Threatened (NT): close to qualifying, or likely to qualify for a threatened category in the near future

Least Concern (LC): population is stable enough that it is unlikely to face extinction in the near future

Least

LC

Data Deficient (DD): not enough information on abundance or distribution to estimate its risk of extinction



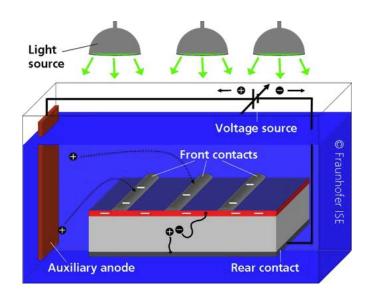
International Union for Conservation of Nature – www.iucn.org

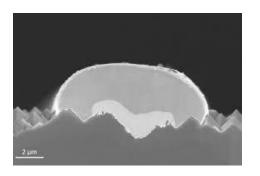


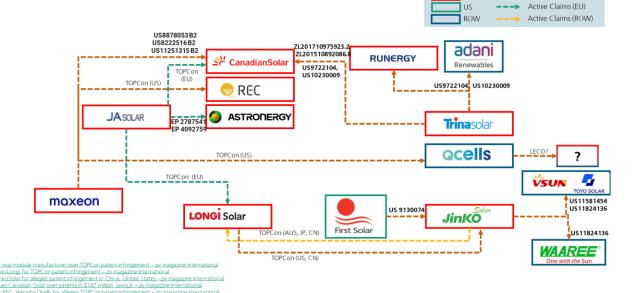
Properties of plated contacts

Plating from aqueous solutions

- Simple, cheap
- Dense, highly conductive layers (close to bulk conductivity)
- Low-Temperature (<60°C)
- Not affected by critical IP
- Limited to certain metals (from aqueous media)
 - Nickel, Copper, Silver, Tin, Zinc, ...
- Requires "prepared" surfaces (see Jonas Eckert's presentation last session)
- Higher process complexity, less workforce







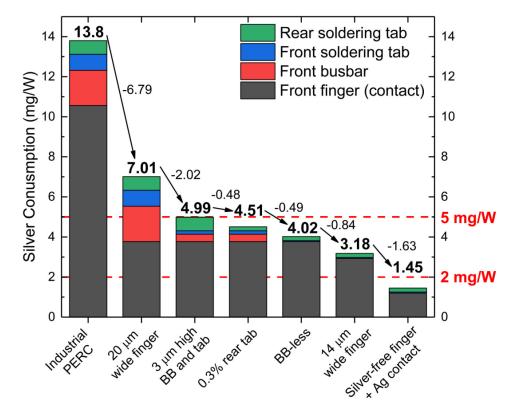
IP restrictions in printed contacts¹



Mainstream – PERC

PERC: Bad Timing

- Process ready for industrial implementation since ~2015
- Would have been needed in 2011
- Meanwhile, much paste reduction
- Limited driving force
- → Plating unlikely to enter (decreasing) PERC production



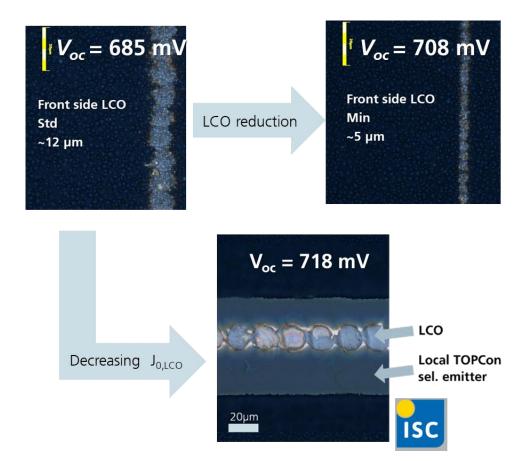
Silver consumption roadmap for printed contacts in PERC cells¹



6

Mainstream - TOPCon

- TOPCon: LECO + paste process too powerful
- Local TOPCon / selective emitter as perspective
- Hybrid process possible Pros and Cons in CoO (50% Ag savings, two techniques, ...)
- Printed copper on the horizon
- → Best chance for plating is local TOPCon front



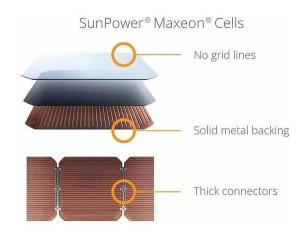
Challenges with V_{OC} in plated contacts on TOPCon^{1,2}

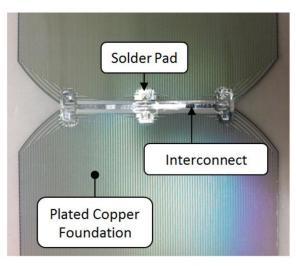


High conductivity / high reliability

Back-Contact Solar Cells

- Only Technology where plating has been used continuously in production (SunPower / Aiko)
- Advantages due to cell design (high conductivity)
- High-end product
- Superior longevity → Plating can be a solution for applications where long lifetime matters
- But: More and more challenged by paste





SunPower Maxeon Cell - Rear

for 20 years in a humid environment). The Conventional Module shows a 28% power loss. This degradation is evidence of water vapor diffusion through the backsheet and around the edges of the cells. This weakens the bonds and corrodes the silver grid lines, resulting in a substantial loss in the ability to carry current. In contrast, the SunPower module (Figure 11, right) appears virtually unchanged. The current carrying copper layer is much more substantial than required to carry the current, proving a large design safety factor. Also it is coated with tin plating, providing a high level of corrosion resistance. The reader will note that the image at far right is not after DH3000, but after DH7750, where it experienced a power loss of 2.7%.

SunPower Module Test Report¹



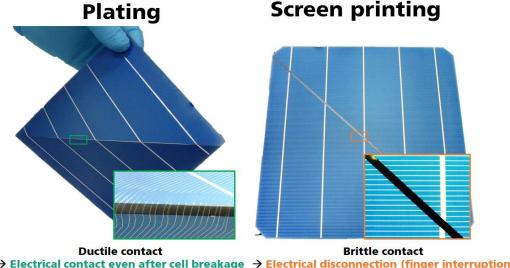
High conductivity / high reliability

Standard Solar Cells

- In principle, similar reliability advantages
- Also shown for BP solar cells (Toledo study)

Shingle Solar Cells

- Longer gridlines can be tolerated
 - → Fewer cuts, less handling etc.



→ Electrical contact even after cell breakage → Electrical disconnection (finger interruption)

Behaviour of plated vs. printed solar cell upon breaking¹

PV modules power degradation has been estimated as 0.2% yearly for BP modules and 1% for Nukem modules in the first 10 years. Degradation increases in last three years to around 1% in BP modules and 2% en NK modules. An extensive campaign of power measurements

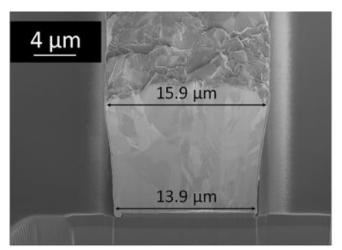
Key result of "Toledo Study"²



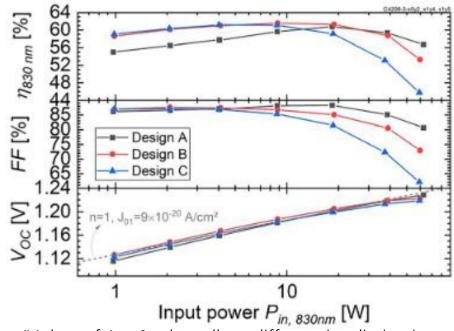
High conductivity / high reliability

Photonic Power Converters (PPCs)

- Very high conductivity needed
- Irradiation as high as possible
- Our best cell: Eta 61.3% @ 18.8W (1cm²!) for 830nm monochromatic irradiation¹



Plated silver contact on PPC¹



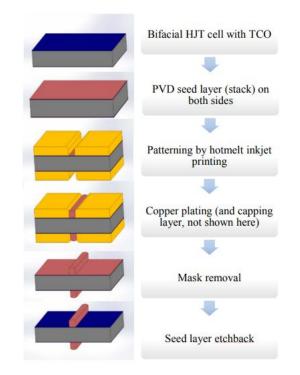
IV-data of 1cm² solar cells at different irradiation intensities¹

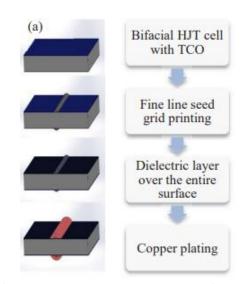


Low thermal budget

Silicon Heterojunction Solar Cells

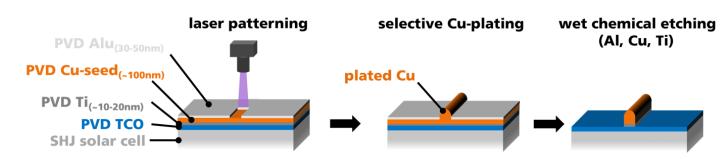
- Currently most in discussions see this session!
- Thermal budget below 240°C
- China moving, lots of plating activities
- Masking of TCO / edge is challenging
- Copper-Containing Low-T Pastes are improving
- → Presently, window of opportunity for plating





Plating on SHJ using printed seed²

Baseline Plating on SHJ¹



NOBLE Process (developed at ISE, now proprietary to PV2+)³

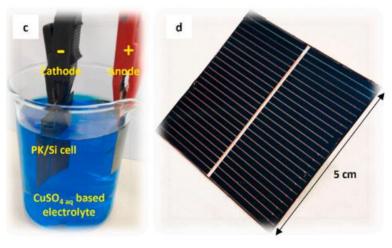
Lachowicz, Agata, et al. "Project ameliz: Patterning techniques for copper electroplated metallization on heterojunction solar cells." AIP Conferent Proceedings. Vol. 2367. No. 1. AIP Publishing LLC, 2021.

³Hatt, Thibaud, et al. "Native oxide barrier layer for selective electroplated metallization of silicon heterojunction solar cells." Solar RRL 3.6 (2019): 1900006.

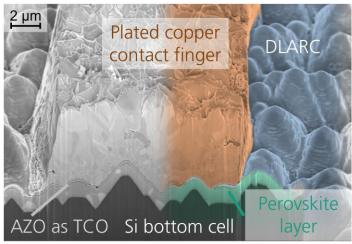
Low thermal budget

Perovskite

- Even higher constraint in thermal budget (ideally <100°C)
- Paste particles can be problematic (rear side, especially TOPCon bottom solar cell)
- Dissolution of sensitive layers is a challenge
 - Already addressed in several publications^{1,2,3}
- But:
 - Conductivity requirements lower
 - ULTP are already catching up



Plating on 5x5cm² Si-Perovskite Tandem solar cell²

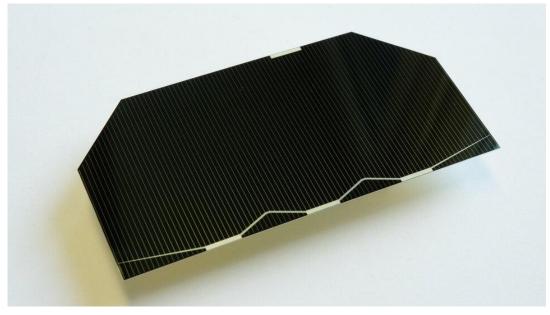


Plating on Si-Perovskite tandem solar cell using Ti-Anodization³

Material incompatibilities

Space Solar Cells

- So far: evaporated contacts
- Volume increases (constellation programmes, LEO satellites), cost reduction desired
- No outgassing tolerable (Space)
- Only qualified materials tolerated
- Application of plating discussed, successful demonstrations (PV2+, Solestial)

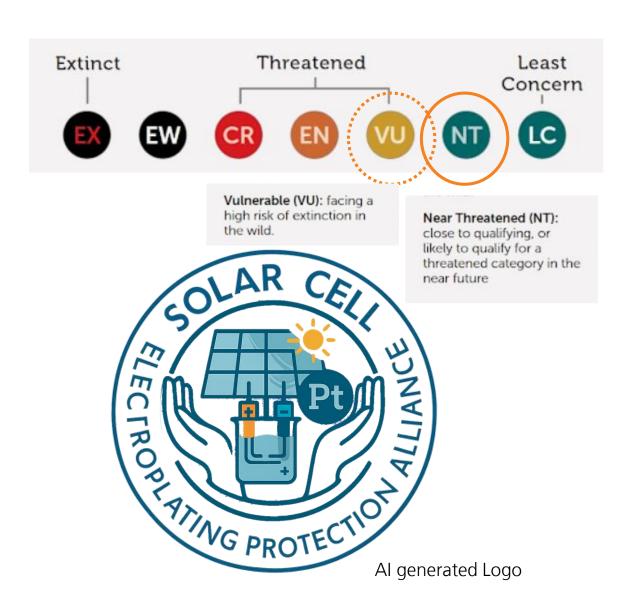


Space Solar Cell¹

Summary & Conclusion

Why should we still consider plating?

- Plating adds unique features to the "gene pool" of PV metallization
- Paste is stronger in current mainstream ecosystems
- Ecological niches for plating for cells with:
 - Limited thermal budget
 - Required superior reliability
 - Very high conductivity needs
 - Difficulties with outgassing / particles
- More and creative approaches are still developed
- Further plating development keeps the PV metallization gene pool diverse and flexible







This work was partially funded by the European Union's Horizon Europe research and innovation programme under grant agreement No 101172902 (Shine PV) and the German Federal Ministry for Economic Affairs and Energy (BMWE) under contract number 03EE1211B (EURO)

